

Low Power Programmable Timing Control Hub™ for P4™ processor

Recommended Application:

Low Power CK505 Compliant Main Clock

Output Features:

- 2 - 0.8V push-pull differential CPU pairs
- 7 - 0.8V push-pull differential PCIEX pairs
- 1 - 0.8V push-pull differential SATA pair
- 1 - 0.8V push-pull differential CPU/PCIEX selectable pair
- 1 - 0.8V push-pull differential 27MHz/LCDCLK/PCIEX selectable pair
- 4 - PCI (33MHz)
- 2 - PCICLK_F, (33MHz) free-running
- 1 - USB, 48MHz
- 1 - DOT96/PCIEX selectable pair
- 2 - REF, 14.318MHz

Key Specifications:

- CPU outputs cycle-cycle jitter < 85ps
- PCIEX outputs cycle-cycle jitter < 125ps
- SATA outputs cycle-cycle jitter < 125ps
- PCI outputs cycle-cycle jitter < 500ps
- +/- 100ppm frequency accuracy on CPU, PCIEX and SATA clocks
- +/- 100ppm frequency accuracy on USB clocks

Features/Benefits:

- Supports tight ppm accuracy clocks for Serial-ATA and PCIEX
- Supports programmable spread percentage and frequency
- Uses external 14.318MHz crystal, external crystal load caps are required for frequency tuning
- PEREQ# pins to support PCIEX power management.
- Low power differential clock outputs (No 50Ω resistor to GND needed)
- iAMT support

Pin Configuration

VDDPC1	1	64	PCICLK0/REQ_SEL**
GND	2	63	PCI/PCIEX_STOP#
PCICLK1	3	62	CPU_STOP#
PCICLK2	4	61	REF1/FSLC/TEST_SEL
*SELPCIEX0_LCD#	5	60	REF0
GND	6	59	GND
VDDPC1	7	58	X1
ITP_EN/PCICLK_F4	8	57	X2
*SELLCD_27#/PCICLK_F5	9	56	VDDREF
VttPWR_GD/PD#	10	55	SDATA
VDD48	11	54	SCLK
FS_A/USB_48MHz	12	53	GND
GND	13	52	CPUT_L0
PCleT_L9/DOT_96MHzL	14	51	CPUC_L0
PCleC_L9/DOTC_96MHzL	15	50	VDDCPU
FS_B/TEST_MODE	16	49	CPUT_L1F
27FIX/LCD_SSCGT/PCleT_L0	17	48	CPUC_L1F
27SS/LCD_SSCGC/PCleC_L0	18	47	VREF
PCleT_L1	19	46	GND
PCleC_L1	20	45	VDDA
VDDPCIEX	21	44	CPUITPT_L2/PCleT_L8
PCleT_L2	22	43	CPUITPC_L2/PCleC_L8
PCleC_L2	23	42	VDDPCIEX
PCleT_L3	24	41	PEREQ1#/PCleT_L7
PCleC_L3	25	40	PEREQ2#/PCleC_L7
SATACLKT_L	26	39	PCleT_L6
SATACLKC_L	27	38	PCleC_L6
VDDPCIEX	28	37	GND
GND	29	36	PCleT_L5
PCleT_L4	30	35	PCleC_L5
PCleC_L4	31	34	PWRSERVE#
*PEREQ3#	32	33	PEREQ4#

ICS9LPR363

64-TSSOP

* Internal Pull-Up Resistor

** Internal Pull-Down Resistor

Note: Please add an external resistor for pull up or down, never rely on an internal resistor when the pin is connected to a device

Latch Select Table

Pin5	Pin9	Pin14/15	Pin17/18
SELPCIEX0_LCD#	SELLCD_27#=0	PCIEX9	27FIX/SS
PCI3 = 0 (low)	SELLCD_27#=1	DOT96	LCD
SELPCIEX0_LCD#	SELLCD_27#=0	PCIEX9	PCIEX0
PCI3 = 1 (high)	SELLCD_27#=1	DOT96	PCIEX0

Functionality Table

FS_LC	FS_LB	FS_LA	CPU MHz	PCI MHz	PCIEX MHz	Spread %
0	0	0	266.66	33.33	100.00	0.5% Down
0	0	1	133.33	33.33	100.00	0.5% Down
0	1	0	200.00	33.33	100.00	0.5% Down
0	1	1	166.66	33.33	100.00	0.5% Down
1	0	0	333.33	33.33	100.00	0.5% Down
1	0	1	100.00	33.33	100.00	0.5% Down
1	1	0	400.00	33.33	100.00	0.5% Down
1	1	1	200.00	33.33	100.00	0.5% Down

Pin Description

PIN #	PIN NAME	TYPE	DESCRIPTION
1	VDDPCI	PWR	Power supply for PCI clocks, nominal 3.3V
2	GND	PWR	Ground pin.
3	PCICLK1	OUT	PCI clock output.
4	PCICLK2	OUT	PCI clock output.
5	*SELPCIEX0_LCD#/PCICLK3	#N/A	#N/A
6	GND	PWR	Ground pin.
7	VDDPCI	PWR	Power supply for PCI clocks, nominal 3.3V
8	ITP_EN/PCICLK_F4	I/O	Free running PCI clock not affected by PCI_STOP#. ITP_EN: latched input to select CPU_ITP/SRC output functionality 1 = CPU_ITP pair 0 = SRC pair
9	*SELLCD_27#/PCICLK_F5	I/O	Free running PCI clock not affected by PCI_STOP#. SELLCD_27#: latched input to select pin functionality. See Latch Select Table
10	VtPWR_GD/PD#	IN	This 3.3V LVTTTL input is a level sensitive strobe used to determine when latch inputs are valid and are ready to be sampled. This is an active high input. / Asynchronous active low input pin used to power down the device into a low power state.
11	VDD48	PWR	Power pin for the 48MHz output.3.3V
12	FSLA/USB_48MHz	I/O	3.3V tolerant input for CPU frequency selection. Refer to input electrical characteristics for Vil_FS and Vih_FS values. / Fixed 48MHz USB clock output. 3.3V.
13	GND	PWR	Ground pin.
14	PCleT_L9/DOTT_96MHzL	OUT	True clock of 0.8V differential push-pull PCI_Express pair / True clock of differential DOT96 output pair. (no 50ohm resistor to GND needed)
15	PCleC_L9/DOTC_96MHzL	OUT	Complement clock of 0.8V differential push-pull PCI_Express pair. / Complement clock of differential DOT96 push-pull output. (no 50ohm resistor to GND needed)
16	FSLB/TEST_MODE	IN	3.3V tolerant input for CPU frequency selection. Refer to input electrical characteristics for Vil_FS and Vih_FS values. TEST_MODE is a real time input to select between Hi-Z and REF/N divider mode while in test mode. Refer to Test Clarification Table.
17	27FIX/LCD_SSCGT/PCleT_L0	OUT	27MHz Non-Spread Push-Pull output / True clock of low power LCDCLK output / True clock of low power PCIEXCLK differential pair/ selected by SELPCIEX0_LCD# and SELLCD_27#. No 50ohm resistor to GND needed for differential outputs.
18	27SS/LCD_SSCGC/PCleC_L0	OUT	27MHz Spreading Push-Pull output / Complementary clock of LCDCLK_SS output / Complementary clock of PCIEXCLK differential pair/ selected by SELPCIEX0_LCD# and SELLCD_27#. No 50ohm resistor to GND needed for differential outputs.
19	PCleT_L1	OUT	True clock of 0.8V differential push-pull PCI_Express pair (no 50ohm resistor to GND needed)
20	PCleC_L1	OUT	Complement clock of 0.8V differential push-pull PCI_Express pair. (no 50ohm resistor to GND needed)
21	VDDPCIEX	PWR	Power supply for PCI Express clocks, nominal 3.3V
22	PCleT_L2	OUT	True clock of 0.8V differential push-pull PCI_Express pair (no 50ohm resistor to GND needed)
23	PCleC_L2	OUT	Complement clock of 0.8V differential push-pull PCI_Express pair. (no 50ohm resistor to GND needed)
24	PCleT_L3	OUT	True clock of 0.8V differential push-pull PCI_Express pair (no 50ohm resistor to GND needed)
25	PCleC_L3	OUT	Complement clock of 0.8V differential push-pull PCI_Express pair. (no 50ohm resistor to GND needed)
26	SATACLKT_L	OUT	True clock of 0.8V push-pull differential SATA pair. (no 50ohm resistor to GND needed)
27	SATACLKC_L	OUT	Complement clock of 0.8V push-pull differential SATA pair. (no 50ohm resistor to GND needed)
28	VDDPCIEX	PWR	Power supply for PCI Express clocks, nominal 3.3V
29	GND	PWR	Ground pin.
30	PCleT_L4	OUT	True clock of 0.8V differential push-pull PCI_Express pair (no 50ohm resistor to GND needed)
31	PCleC_L4	OUT	Complement clock of 0.8V differential push-pull PCI_Express pair. (no 50ohm resistor to GND needed)
32	*PEREQ3#	IN	Real-time input pin that controls PCIEXCLK outputs that are selected through the I2c. 1 = disabled, 0 = enabled.

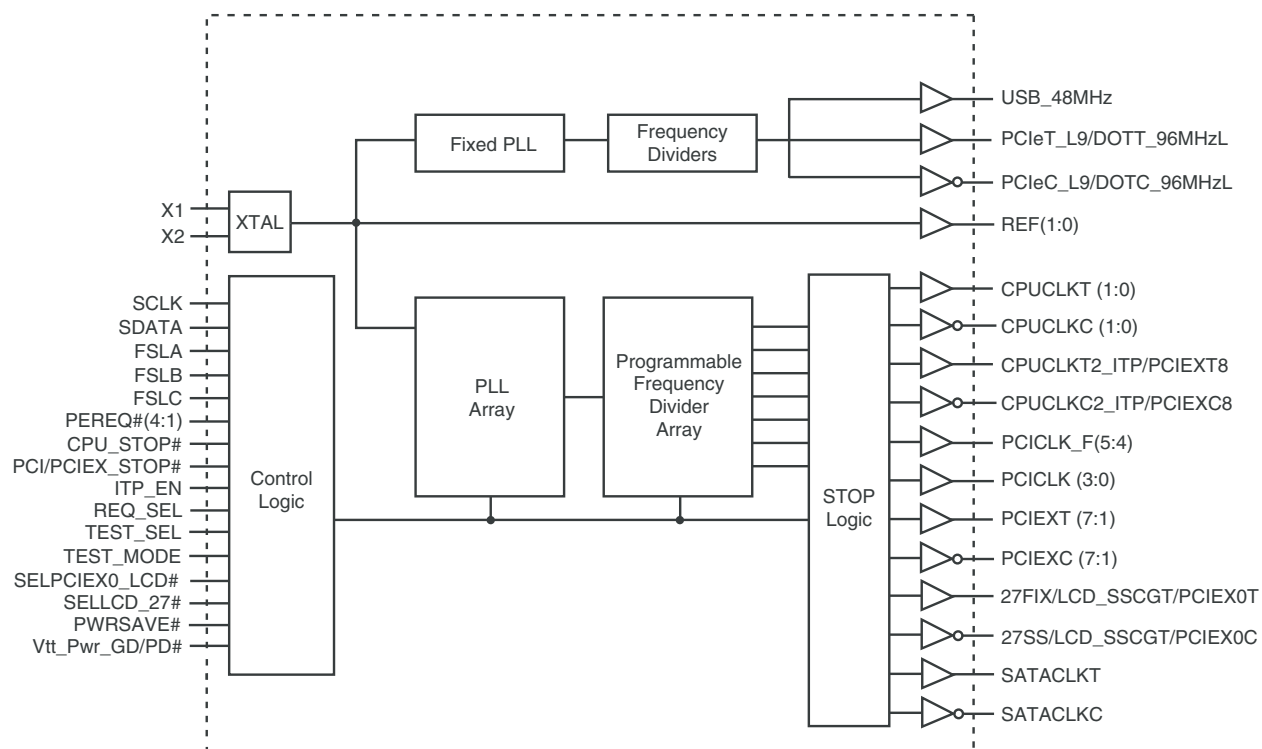
Pin Description (Continued)

PIN #	PIN NAME	TYPE	DESCRIPTION
33	PEREQ4#*	IN	Real-time input pin that controls PCIEXCLK outputs that are selected through the I2c. 1 = disabled, 0 = enabled.
34	PWRSAVE#*	IN	Active-low input pin used to change frequency to underclocked entries in the ROM table that can be pre-programmed through Byte 6 of the I2c.
35	PCleC_L5	OUT	Complement clock of 0.8V differential push-pull PCI_Express pair. (no 50ohm resistor to GND needed)
36	PCleT_L5	OUT	True clock of 0.8V differential push-pull PCI_Express pair (no 50ohm resistor to GND needed)
37	GND	PWR	Ground pin.
38	PCleC_L6	OUT	Complement clock of 0.8V differential push-pull PCI_Express pair. (no 50ohm resistor to GND needed)
39	PCleT_L6	OUT	True clock of 0.8V differential push-pull PCI_Express pair (no 50ohm resistor to GND needed)
40	PEREQ2#/PCleC_L7	I/O	Real-time input pin that controls PCIEXCLK outputs that are selected through the I2c. 1 = disabled, 0 = enabled. / Complement clock of differential low power PCI Express output. No 50ohm resistor to GND needed.
41	PEREQ1#/PCleT_L7	I/O	Real-time input pin that controls PCIEXCLK outputs that are selected through the I2c. 1 = disabled, 0 = enabled. / True clock of differential low power PCI Express output. No 50ohm resistor to GND needed.
42	VDDPCIEX	PWR	Power supply for PCI Express clocks, nominal 3.3V
43	CPUITPC_L2/PCleC_L8	OUT	Complement clock of differential pair CPU output. / Complement clock of differential PCIEX pair. These are 0.8V push pull outputs. No 50ohm resistor to GND needed.
44	CPUITPT_L2/PCleT_L8	OUT	True clock of differential pair CPU output. / True clock of differential PCIEX pair. These are 0.8V push pull outputs. No 50ohm resistor to GND needed.
45	VDDA	PWR	3.3V power for the PLL core.
46	GNDA	PWR	Ground pin for the PLL core.
47	VREF	PWR	Voltage reference for low power outputs.
48	CPUC_L1F	OUT	Complementary clock of differential pair of low power CPU outputs. Free running during iAMT. No 50ohm resistor to GND needed.
49	CPUT_L1F	OUT	True clock of differential pair of low power CPU outputs. Free running during iAMT. No 50ohm resistor to GND needed.
50	VDDCPU	PWR	Supply for CPU clocks, 3.3V nominal
51	CPUC_L0	OUT	Complementary clock of differential pair 0.8V push-pull CPU outputs. No 50ohm resistor to GND needed.
52	CPUT_L0	OUT	True clock of differential pair 0.8V push-pull CPU outputs. No 50ohm resistor to GND needed.
53	GND	PWR	Ground pin.
54	SCLK	IN	Clock pin of SMBus circuitry, 5V tolerant.
55	SDATA	I/O	Data pin for SMBus circuitry, 5V tolerant.
56	VDDREF	PWR	Ref, XTAL power supply, nominal 3.3V
57	X2	OUT	Crystal output, Nominally 14.318MHz
58	X1	IN	Crystal input, Nominally 14.318MHz.
59	GND	PWR	Ground pin.
60	REF0	OUT	14.318 MHz reference clock.
61	REF1/FSLC/TEST_SEL	I/O	14.318 MHz reference clock./ 3.3V tolerant input for CPU frequency selection. Refer to input electrical characteristics for Vil_FS and Vih_FS values. /TEST_Sel: 3-level latched input to enable test mode. Refer to Test Clarification Table
62	CPU_STOP#	IN	Stops all CPUCLK, except those set to be free running clocks
63	PCI/PCIEX_STOP#	IN	Stops all PCICLKs and PCIEXCLKs besides the free-running clocks at logic 0 level, when input low
64	PCICLK0/REQ_SEL**	I/O	3.3V PCI clock output / Latch select input pin. 0 = PCIEXCLK, 1 = PEREQ#

General Description

ICS9LPR363 is a low power CK505-compliant clock specification. This clock synthesizer provides a single chip solution for next generation P4 Intel processors and Intel chipsets. **ICS9LPR363** is driven with a 14.318MHz crystal.

Block Diagram



Note: 1. VREF is not connected unless differential amplitude needs to be tuned

Power Supply

PIN NUMBER		Description
VDD	GND	
1,7	2,6	PCICLK outputs
11	13	48MHz,96Mhz, LCDCLK, Fix Digital, Fix Analog
45	46	Master clock, CPU Analog
28, 42	21, 29, 37	PCIEXT/C outputs
50	53	CPUT/C output
56	59	Xtal, REF

Differential Amplitude control using VREF.

Rpull-up: Connected between Vref and Vdd=3.3V;

Rpull-down: Connected between Vref and GND

Keep Rpull-up=1K ohm and variable Rpull-down to measure CPU and PCIEX Vtop

Rpull-up (ohm)	Rpull-down (ohm)	CPU-T Vtop (mV)	PCIEX-T Vtop (mV)	SATA-T Vtop (mV)
1K	200	1155	1149	1136
1K	221	1092	1060	1063
1K	239	1054	1028	1040
1K	270	996	991	984
1K	301	943	946	931
1K	330	924	913	912
1K	360	898	888	885
1K	375	871	860	865
1K	390	867	837	822
1K	414	812	822	801

*Measurement based on Vtop-avg

**Test board trace impedance is 50ohms

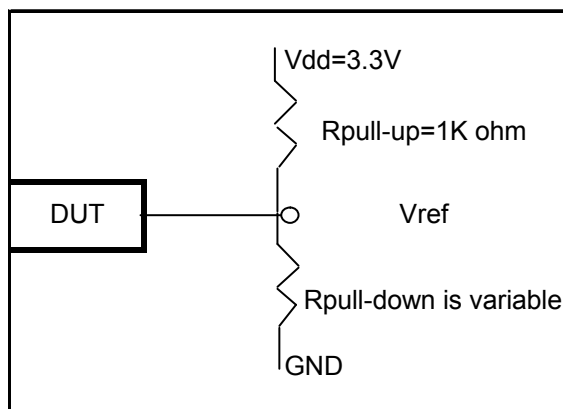


Table 1: CPU/PCIEX Frequency Selection Table

FS4	FS3	FS _L C	FS _L B	FS _L A	CPU MHz	PCI MHz	PCIEX MHz	Spread %
0	0	0	0	0	266.66	33.33	100.00	0.5% Down
0	0	0	0	1	133.33	33.33	100.00	0.5% Down
0	0	0	1	0	200.00	33.33	100.00	0.5% Down
0	0	0	1	1	166.66	33.33	100.00	0.5% Down
0	0	1	0	0	333.33	33.33	100.00	0.5% Down
0	0	1	0	1	100.00	33.33	100.00	0.5% Down
0	0	1	1	0	400.00	33.33	100.00	0.5% Down
0	0	1	1	1	200.00	33.33	100.00	0.5% Down
0	1	0	0	0	266.66	33.33	100.00	+/- 0.25 Center
0	1	0	0	1	133.33	33.33	100.00	+/- 0.25 Center
0	1	0	1	0	200.00	33.33	100.00	+/- 0.25 Center
0	1	0	1	1	166.66	33.33	100.00	+/- 0.25 Center
0	1	1	0	0	333.33	33.33	100.00	+/- 0.25 Center
0	1	1	0	1	100.00	33.33	100.00	+/- 0.25 Center
0	1	1	1	0	400.00	33.33	100.00	+/- 0.25 Center
0	1	1	1	1	200.00	33.33	100.00	+/- 0.25 Center
1	0	0	0	0	261.33	32.66	98	+/- 0.25 Center
1	0	0	0	1	130.66	32.66	98	+/- 0.25 Center
1	0	0	1	0	196.00	32.66	98	+/- 0.25 Center
1	0	0	1	1	163.33	32.66	98	+/- 0.25 Center
1	0	1	0	0	253.33	31.66	95	+/- 0.25 Center
1	0	1	0	1	126.66	31.66	95	+/- 0.25 Center
1	0	1	1	0	190.00	31.66	95	+/- 0.25 Center
1	0	1	1	1	158.33	31.66	95	+/- 0.25 Center
1	1	0	0	0	247.99	31.00	93	+/- 0.25 Center
1	1	0	0	1	124.00	31.00	93	+/- 0.25 Center
1	1	0	1	0	186.00	31.00	93	+/- 0.25 Center
1	1	0	1	1	154.99	31.00	93	+/- 0.25 Center
1	1	1	0	0	239.99	30.00	90	+/- 0.25 Center
1	1	1	0	1	120.00	30.00	90	+/- 0.25 Center
1	1	1	1	0	180.00	30.00	90	+/- 0.25 Center
1	1	1	1	1	149.99	30.00	90	+/- 0.25 Center

Table2: LCDCLK Spread and Frequency Selection Table

SELDOT_27#	Byte 9b7 SS3	Byte9b6 SS2	Byte 9b5 SS1	Byte 9b4 SS0	Pin 17/18	Spread	
					MHz	%	
0	0	0	0	0	27.00	+/-0.25	Center
0	0	0	0	1	27.00	+/-0.50	Center
0	0	0	1	0	27.00	+/-0.75	Center
0	0	0	1	1	27.00	+/-1.0	Center
0	0	1	0	0	27.00	+/-1.25	Center
0	0	1	0	1	27.00	+/-1.5	Center
0	0	1	1	0	27.00	+/-1.75	Center
0	0	1	1	1	27.00	+/-2	Center
0	1	0	0	0	27.00	-0.5	Down
0	1	0	0	1	27.00	-1	Down
0	1	0	1	0	27.00	-1.25	Down
0	1	0	1	1	27.00	-1.5	Down
0	1	1	0	0	27.00	-1.75	Down
0	1	1	0	1	27.00	-2	Down
0	1	1	1	0	27.00	-2.5	Down
0	1	1	1	1	27.00	-3	Down
1	0	0	0	0	96.00	+/-1.5	Center
1	0	0	0	1	96.00	+/-1.25	Center
1	0	0	1	0	96.00	+/-1.0	Center
1	0	0	1	1	96.00	+/-0.8	Center
1	0	1	0	0	96.00	+/-0.6	Center
1	0	1	0	1	96.00	+/-0.5	Center
1	0	1	1	0	96.00	+/-0.4	Center
1	0	1	1	1	96.00	+/-0.3	Center
1	1	0	0	0	96.00	3	Down
1	1	0	0	1	96.00	2.5	Down
1	1	0	1	0	96.00	2	Down
1	1	0	1	1	96.00	1.75	Down
1	1	1	0	0	96.00	1.5	Down
1	1	1	0	1	96.00	1.25	Down
1	1	1	1	0	96.00	1	Down
1	1	1	1	1	96.00	0.8	Down

Table3: SATA Spread and Frequency Selection Table

SEL_SATA	Byte 16b3 SS3	Byte16b2 SS2	Pin 27/26	Spread	
			MHz	%	
1	0	0	100.00	-0.2	Down
1	0	1	100.00	-0.3	Down
1	1	0	100.00	-0.4	Down
1	1	1	100.00	-0.5	Down

CPU Power Management Table

PWRDWN#	CPU_STOP#	PCI_STOP#	PEREQ#	SMBus Register OE	CPU1	CPU1#	CPU0	CPU0#
1	1	1	X	Enable	Running	Running	Running	Running
0	X	X	X	Enable	Low/20K	Low	Low/20K	Low
1	0	X	X	Enable	High	Low	High	Low
1	X	X	X	Disable	Low/20K	Low	Low/20K	Low
M1					Running	Running	Low/20K	Low

PCIe, LCD, DOT Power Management Table

PWRDWN#	CPU_STOP#	PCI_STOP#	PEREQ#		PCIe/LCD	PCIe#/LCD#	PCIe/LCD	PCIe#/LCD#	DOT	DOT#
					Free-Run		PCI Stoppable/ PEREQ Selected			
1	X	1	0	Enable	Running	Running	Running	Running	Running	Running
0	X	X	X	Enable	Low/20K	Low	Low/20K	Low	Low/20K	Low
1	X	0	X	Enable	Running	Running	High	Low	Running	Running
1	X	X	1	Enable	Running	Running	Low/20K	Low	Running	Running
1	X	X	X	Disable	Low/20K	Low	Low/20K	Low	Low/20K	Low
M1					Low/20K	Low	Low/20K	Low	Low/20K	Low

Singled-ended Power Management Table

PWRDWN#	CPU_STOP#	PCI_STOP#	PEREQ#	SMBus Register OE	PCIF/PCI	PCIF/PCI	USB	REF
					Free-run	Stoppable		
1	X	1	X	Enable	Running	Running	Running	Running
0	X	X	X	Enable	Low	Low	Low	Low
1	X	0	X	Enable	Running	Low	Running	Running
1	X	X	X	Disable	Low	Low	Low	Low
M1					Low	Low	Low	Low

General I²C serial interface information for the ICS9LPR363

How to Write:

- Controller (host) sends a start bit.
- Controller (host) sends the write address D2_(H)
- ICS clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- ICS clock will **acknowledge**
- Controller (host) sends the data byte count = X
- ICS clock will **acknowledge**
- Controller (host) starts sending **Byte N through Byte N + X - 1**
(see Note 2)
- ICS clock will **acknowledge** each byte **one at a time**
- Controller (host) sends a Stop bit

How to Read:

- Controller (host) will send start bit.
- Controller (host) sends the write address D2_(H)
- ICS clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- ICS clock will **acknowledge**
- Controller (host) will send a separate start bit.
- Controller (host) sends the read address D3_(H)
- ICS clock will **acknowledge**
- ICS clock will send the data byte count = X
- ICS clock sends **Byte N + X - 1**
- ICS clock sends **Byte 0 through byte X (if X_(H) was written to byte 8).**
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

Index Block Write Operation		
Controller (Host)		ICS (Slave/Receiver)
T	starT bit	
Slave Address D2 _(H)		
WR	WRite	
		ACK
Beginning Byte = N		
		ACK
Data Byte Count = X		
		ACK
Beginning Byte N		
		ACK
○		
○		○
○		○
		○
Byte N + X - 1		
		ACK
P	stoP bit	

Index Block Read Operation		
Controller (Host)		ICS (Slave/Receiver)
T	starT bit	
Slave Address D2 _(H)		
WR	WRite	
		ACK
Beginning Byte = N		
		ACK
RT	Repeat starT	
Slave Address D3 _(H)		
RD	ReaD	
		ACK
		Data Byte Count = X
ACK		
		Beginning Byte N
ACK		
○		○
○		○
○		○
		Byte N + X - 1
N	Not acknowledge	
P	stoP bit	

I2C Table: Output Control Register

Byte 0	Name	Control Function	Type	0	1	PWD
Bit 7	CPUCLK2_ITP/PCIEX8 Enable	Output Enable	RW	Disable (HiZ)	Enable	1
Bit 6	PCIEX7 Enable	Output Enable	RW	Disable (HiZ)	Enable	1
Bit 5	PCIEX5 Enable	Output Enable	RW	Disable (HiZ)	Enable	1
Bit 4	PCIEX4 Enable	Output Enable	RW	Disable (HiZ)	Enable	1
Bit 3	PCIEX3 Enable	Output Enable	RW	Disable (HiZ)	Enable	1
Bit 2	PCIEX2 Enable	Output Enable	RW	Disable (HiZ)	Enable	1
Bit 1	PCIEX1 Enable	Output Enable	RW	Disable (HiZ)	Enable	1
Bit 0	LCD/PCIEX0 Enable	Output Enable	RW	Disable (HiZ)	Enable	1

I2C Table: Output Control Register

Byte 1	Name	Control Function	Type	0	1	PWD
Bit 7	PCICLK_2	Output Enable	RW	Disable	Enable	1
Bit 6	PCIEX9/DOT_96MHz Enable	Output Enable	RW	Disable (HiZ)	Enable	1
Bit 5	USB_48MHz Enable	Output Enable	RW	Disable	Enable	1
Bit 4	REF1 Enable	Output Enable	RW	Disable	Enable	1
Bit 3	PCIEX6 Enable	Output Enable	RW	Disable (HiZ)	Enable	1
Bit 2	CPUCLK_1 Enable	Output Enable	RW	Disable (HiZ)	Enable	1
Bit 1	CPUCLK_0 Enable	Output Enable	RW	Disable (HiZ)	Enable	1
Bit 0	Spread Spectrum Mode (CPU, PCIEX, PCIF, PCI)	Spread Control for PLL1	RW	SPREAD OFF	SPREAD ON	1

I2C Table: Output Control Register

Byte 2	Name	Control Function	Type	0	1	PWD
Bit 7	PCICLK1	Output Enable	RW	Disable	Enable	1
Bit 6	PCICLK0	Output Enable	RW	Disable	Enable	1
Bit 5	PCICLK_F5	Output Enable	RW	Disable	Enable	1
Bit 4	PCICLK_F4	Output Enable	RW	Disable	Enable	1
Bit 3	PCICLK3	Output Enable	RW	Disable	Enable	1
Bit 2	27MHz (Fixed)	Output Enable	RW	Disable	Enable	1
Bit 1	27MHz (SS)	Output Enable	RW	Disable	Enable	1
Bit 0	SATACLK	Output Enable	RW	Disable (HiZ)	Enable	1

I2C Table: Output Control Register

Byte 3	Name	Control Function	Type	0	1	PWD
Bit 7	PCIEX6	Allow assertion of PCI_STOP# or setting of PCI_STOP control bit in I2C register to stop PCIEX clocks.	RW	Free-Running	Stoppable	0
Bit 6	PCIEX5		RW	Free-Running	Stoppable	0
Bit 5	PCIEX4		RW	Free-Running	Stoppable	0
Bit 4	SATACLK		RW	Free-Running	Stoppable	0
Bit 3	PCIEX3		RW	Free-Running	Stoppable	0
Bit 2	PCIEX2		RW	Free-Running	Stoppable	0
Bit 1	PCIEX1		RW	Free-Running	Stoppable	0
Bit 0	PCIEX0		RW	Free-Running	Stoppable	0

I2C Table: Output Control Register

Byte 4	Name	Control Function	Type	0	1	PWD
Bit 7	PCIEX7	Free-Running Control	RW	Free-Running	Stoppable	0
Bit 6	PCIEX9	Free-Running Control	RW	Free-Running	Stoppable	0
Bit 5	PCIEX8	Free-Running Control	RW	Free-Running	Stoppable	0
Bit 4	PCICLK_F5	Allow assertion of PCI_STOP# or setting of PCI_STOP control bit in SMBus register to stop PCI clocks.	RW	Free-Running	Stoppable	0
Bit 3	PCICLK_F4		RW	Free-Running	Stoppable	0
Bit 2	CPUCLK_2/ITP	Allow assertion of CPU_STOP# to stop CPU clocks.	RW	Free-Running	Stoppable	0
Bit 1	CPUCLK_1		RW	Free-Running	Stoppable	0
Bit 0	CPUCLK_0		RW	Free-Running	Stoppable	0

I2C Table: Output Control Register

Byte 5	Name	Control Function	Type	0	1	PWD
Bit 7	Reserved	Reserved	RW	-	-	0
Bit 6	PCICLK0	Strength Control	RW	1x	2x	0
Bit 5	Reserved	Reserved	RW	-	-	0
Bit 4	Reserved	Reserved	RW	-	-	0
Bit 3	Reserved	Reserved	RW	-	-	0
Bit 2	PCICLK1	Strength Control	RW	1x	2x	0
Bit 1	Reserved	Reserved	RW	-	-	0
Bit 0	Reserved	Reserved	RW	-	-	0

I2C Table: Frequency Select Register

Byte 6	Name	Control Function	Type	0	1	PWD
Bit 7	PWRSAVE	PWR_SAVE programming	RW	IIC	PWR_SAVE programming	0
Bit 6	FS4	Frequency Select bit	RW	See Table 1: Frequency Selection Table		0
Bit 5	FS3	Frequency Select bit	RW			0
Bit 4	REF0 STRENGTH	Strength Prog	RW	1X	2X	0
Bit 3	PCI/SRC_STOP#	Stop all PCI and SRC clocks	RW	Outputs Stopped	Outputs Active	1
Bit 2	FSL_C	Frequency Select bit	RW	See Table 1: Frequency Selection Table		latch
Bit 1	FSL_B	Frequency Select bit	RW			latch
Bit 0	FSL_A	Frequency Select bit	RW			latch

I2C Table: Revision and Vendor ID Register

Byte 7	Name	Control Function	Type	0	1	PWD
Bit 7	RID3	Revision ID	R	-	-	0
Bit 6	RID2		R	-	-	0
Bit 5	RID1		R	-	-	0
Bit 4	RID0		R	-	-	0
Bit 3	VID3	VENDOR ID	R	-	-	0
Bit 2	VID2		R	-	-	0
Bit 1	VID1		R	001 = ICS	-	0
Bit 0	VID0		R	-	-	1

I2C Table: PEREQ Control Register

Byte 8	Name	Control Function	Type	0	1	PWD
Bit 7	PEREQ2# Control	PCIEX8 is controlled	RW	Not Controlled	Controlled	0
Bit 6	PEREQ2# Control	PCIEX1 is controlled	RW	Not Controlled	Controlled	0
Bit 5	iAMT_EN	Set via SMBus or dynamically by CK505 if detects dynamic M1	RW	Legacy Mode	iAMT Enabled	0
Bit 4	PD_Restore	If config saved, on deassert return to last known state else clear all config as if cold power on and go to latches open state	RW	Configuration Not Saved	Configuration Saved	1
Bit 3	Reserved	Reserved	RW	-	-	1
Bit 2	PEREQ1# Control	SATACLK is controlled	RW	Not Controlled	Controlled	0
Bit 1	PEREQ1# Control	PCIEX6 is controlled	RW	Not Controlled	Controlled	0
Bit 0	PEREQ1# Control	PCIEX0 is controlled	RW	Not Controlled	Controlled	0

I2C Table: LCDCLK and M/N Control Register

Byte 9	Name	Control Function	Type	0	1	PWD
Bit 7	LCDCLK_SS3	Bit S3	RW	See LCDCLK_SS and 27Mhz Spread Select Table 2		0
Bit 6	LCDCLK_SS2	Bit S2	RW			1
Bit 5	LCDCLK_SS1	Bit S1	RW			1
Bit 4	LCDCLK_SS0	Bit S0	RW			1
Bit 3	*SEL SRC_LCDCLK#	Selects SRC or LCD/27MHz on pins 17 and 18	R	LCDCLK	PCIEX0	latch
Bit 2	REF 0	Output Enable	RW	Disable	Enable	1
Bit 1	LCDCLK_SS Spread Enable	Enable SS	RW	OFF	ON	1
Bit 0	M/N Enable	PLL M/N Programming Enable	RW	Disable	Enable	0

I2C Table: Byte Count Register

Byte 10	Name	Control Function	Type	0	1	PWD
Bit 7	Reserved	Reserved	RW	-	-	X
Bit 6	Reserved	Reserved	RW	-	-	X
Bit 5	Reserved	Reserved	RW	-	-	X
Bit 4	BC4	Byte Count Programming b(7:0)	RW	Writing to this register will configure how many bytes will be read back, default is 15 = 21 Bytes.		1
Bit 3	BC3		RW			0
Bit 2	BC2		RW			1
Bit 1	BC1		RW			0
Bit 0	BC0		RW			1

I2C Table: PLL1 Frequency Control Register

Byte 11	Name	Control Function	Type	0	1	PWD
Bit 7	N Div8	N Divider Prog bit 8	RW	The decimal representation of M and N Divider in Byte 11 and 12 will configure the VCO frequency. Default at power up = latch-in or Byte 0 Rom table. VCO Frequency = 14.318 x [NDiv(9:0)+8] / [MDiv(5:0)+2]		X
Bit 6	N Div 9	N Divider Prog bit 9	RW			X
Bit 5	M Div5	M Divider Programming bits	RW			X
Bit 4	M Div4		RW			X
Bit 3	M Div3		RW			X
Bit 2	M Div2		RW			X
Bit 1	M Div1		RW			X
Bit 0	M Div0		RW			X

I²C Table: PLL1 Frequency Control Register

Byte 12	Name	Control Function	Type	0	1	PWD
Bit 7	N Div7	N Divider Programming b(8:0)	RW	The decimal representation of M and N Divider in Byte 11 and 12 will configure the VCO frequency. Default at power up = latch-in or Byte 0 Rom table. VCO Frequency = 14.318 x [NDiv(9:0)+8] / [MDiv(5:0)+2]		X
Bit 6	N Div6		RW			X
Bit 5	N Div5		RW			X
Bit 4	N Div4		RW			X
Bit 3	N Div3		RW			X
Bit 2	N Div2		RW			X
Bit 1	N Div1		RW			X
Bit 0	N Div0		RW			X

I²C Table: PLL1 Spread Spectrum Control Register

Byte 13	Name	Control Function	Type	0	1	PWD
Bit 7	SSP7	Spread Spectrum Programming bit(7:0)	RW	These Spread Spectrum bits in Byte 13 and 14 will program the spread percentage of PLL1		X
Bit 6	SSP6		RW			X
Bit 5	SSP5		RW			X
Bit 4	SSP4		RW			X
Bit 3	SSP3		RW			X
Bit 2	SSP2		RW			X
Bit 1	SSP1		RW			X
Bit 0	SSP0		RW			X

I²C Table: PLL1 Spread Spectrum Control Register

Byte 14	Name	Control Function	Type	0	1	PWD
Bit 7	Reserved	Reserved	R	-	-	0
Bit 6	SSP14	Spread Spectrum Programming bit(14:8)	RW	These Spread Spectrum bits in Byte 13 and 14 will program the spread percentage of PLL1		X
Bit 5	SSP13		RW			X
Bit 4	SSP12		RW			X
Bit 3	SSP11		RW			X
Bit 2	SSP10		RW			X
Bit 1	SSP9		RW			X
Bit 0	SSP8		RW			X

I²C Table: PEREQ Control Register

Byte 15	Name	Control Function	Type	0	1	PWD
Bit 7	PEREQ4# Control	PCIEX7 is controlled	RW	Not Controlled	Controlled	0
Bit 6	PEREQ4# Control	PCIEX5 is controlled	RW	Not Controlled	Controlled	0
Bit 5	PEREQ4# Control	PCIEX3 is controlled	RW	Not Controlled	Controlled	0
Bit 4	Reserved	Reserved	RW	-	-	0
Bit 3	Reserved	Reserved	RW	-	-	0
Bit 2	Reserved	Reserved	RW	-	-	0
Bit 1	PEREQ3# Control	PCIEX4 is controlled	RW	Not Controlled	Controlled	0
Bit 0	PEREQ3# Control	PCIEX2 is controlled	RW	Not Controlled	Controlled	0

I²C Table: SATACLK Control Register

Byte 16	Name	Control Function	Type	0	1	PWD
Bit 7	SEL_SATA	SATACLK Spread Control	RW	PCIEX PLL	SATA PLL	1
Bit 6	SEL_LCD(27#)	Select LCD or 27MHz for pins 17 and 18	RW	27MHz/PCIEX9	LCDCLK/DOT96	latch
Bit 5	PCIEX source	PCIEX comes from	RW	PCIEX PLL	SATA PLL	0
Bit 4	SATA_SS ENABLE	SPREAD ENABLE SATA PLL	RW	OFF	ON	1
Bit 3	SATA_SS1	Bit S1	RW	See SATA_SS Frequency Select Table 3		1
Bit 2	SATA_SS0	Bit S0	RW			1
Bit 1	PCI source	PCI comes from	RW	PCIEX PLL	SATA PLL	0
Bit 0	PCICLK2	Strength Control	RW	1x	2x	0

I²C Table: PLL2 Frequency Control Register

Byte 17	Name	Control Function	Type	0	1	PWD
Bit 7	N Div8	N Divider Prog bit 8	RW	The decimal representation of M and N Divider in Byte 17 and 18 will configure the VCO frequency. Default at power up = Byte 0 Rom table. VCO Frequency = 14.318 x [NDiv(9:0)+8] / [MDiv(5:0)+2]		X
Bit 6	N Div9	N Divider Prog bit 9	RW			X
Bit 5	M Div5	M Divider Programming bits	RW			X
Bit 4	M Div4		RW			X
Bit 3	M Div3		RW			X
Bit 2	M Div2		RW			X
Bit 1	M Div1		RW			X
Bit 0	M Div0		RW			X

I²C Table: PLL2 Frequency Control Register

Byte 18	Name	Control Function	Type	0	1	PWD
Bit 7	N Div7	N Divider Programming b(8:0)	R	The decimal representation of M and N Divider in Byte 17 and 18 will configure the VCO frequency. Default at power up = Byte 0 Rom table. VCO Frequency = 14.318 x [NDiv(9:0)+8] / [MDiv(5:0)+2]		X
Bit 6	N Div6		RW			X
Bit 5	N Div5		RW			X
Bit 4	N Div4		RW			X
Bit 3	N Div3		RW			X
Bit 2	N Div2		RW			X
Bit 1	N Div1		RW			X
Bit 0	N Div0		RW			X

I²C Table: PLL 2 Spread Spectrum Control Register

Byte 19	Name	Control Function	Type	0	1	PWD
Bit 7	SSP7	Spread Spectrum Programming b(7:0)	RW	These Spread Spectrum bits in Byte 19 and 20 will program the spread percentage. It is recommended to use ICS Spread % table for spread programming.		X
Bit 6	SSP6		RW			X
Bit 5	SSP5		RW			X
Bit 4	SSP4		RW			X
Bit 3	SSP3		RW			X
Bit 2	SSP2		RW			X
Bit 1	SSP1		RW			X
Bit 0	SSP0		RW			X

I²C Table: PLL 2 Spread Spectrum Control Register

Byte 20	Name	Control Function	Type	0	1	PWD
Bit 7	Reserved	Reserved	RW	These Spread Spectrum bits in Byte 19 and 20 will program the spread percentage. It is recommended to use ICS Spread % table for spread programming.		0
Bit 6	SSP14	Spread Spectrum Programming b(14:8)	RW			X
Bit 5	SSP13		RW			X
Bit 4	SSP12		RW			X
Bit 3	SSP11		RW			X
Bit 2	SSP10		RW			X
Bit 1	SSP9		RW			X
Bit 0	SSP8		RW			X

Test Clarification Table

Comments	HW		OUTPUT
	FSLC/ TEST_SEL HW PIN	FSLB/ TEST_MODE HW PIN	
	<1.14V	X	NORMAL
Power-up w/ TEST_SEL = 1 to enter test mode Cycle power to disable test mode FSLC./TEST_SEL -->3-level latched input If power-up w/ V>1.14V then use TEST_SEL	>1.14V	0	HI-Z
If power-up w/ V<1.14V then use FSLC FSLB/TEST_MODE -->low Vth input TEST_MODE is a real time input	>1.14V	1	REF/N

Absolute Maximum Ratings

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS	Notes
Maximum Supply Voltage	VDDxxx	Supply Voltage		4.6	V	1,3
Maximum Input Voltage	V _{IH}	3.3V LVCMOS Inputs		4.6	V	1,3,4
Minimum Input Voltage	V _{IL}	Any Input	GND - 0.5		V	1,3
Storage Temperature	T _s	-	-65	150	°C	1,3
Case Temperature	T _{case}	-		115	°C	1,3
Input ESD protection	ESD prot	Human Body Model	2000		V	1,3

¹Guaranteed by design and characterization, not 100% tested in production.

²Input frequency should be measured at the REF pin and tuned to ideal 14.31818MHz to meet ppm frequency accuracy on PLL outputs.

³Operation under these conditions is neither implied, nor guaranteed.

⁴Maximum input voltage is not to exceed VDD

Electrical Characteristics - Input/Supply/Common Output Parameters

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS	Notes
Ambient Operating Temp	T _{ambient}	-	0	70	°C	1
Supply Voltage	VDDxxx	Supply Voltage	3.135	3.465	V	1
Input High Voltage	V _{IHSE}	Single-ended inputs	2	V _{DD} + 0.3	V	1
Input Low Voltage	V _{ILSE}	Single-ended inputs	V _{SS} - 0.3	0.8	V	1
Input Leakage Current	I _{IN}	V _{IN} = V _{DD} , V _{IN} = GND	-5	5	uA	1
Input Leakage Current	I _{INRES}	Inputs with pull or pull down resistors V _{IN} = V _{DD} , V _{IN} = GND	-200	200	uA	1
Output High Voltage	V _{OHSE}	Single-ended outputs, I _{OH} = -1mA	2.4		V	1
Output Low Voltage	V _{OLSE}	Single-ended outputs, I _{OL} = 1 mA		0.4	V	1
Output High Voltage	V _{OHDIFF}	Differential Outputs, I _{OH} = TBD mA			V	1
Output Low Voltage	V _{OLDIFF}	Differential Outputs, I _{OL} = TBD mA		0.4	V	1
Low Threshold Input-High Voltage	V _{IH_FS}	3.3 V +/-5%	0.7	V _{DD} + 0.3	V	1
Low Threshold Input-Low Voltage	V _{IL_FS}	3.3 V +/-5%	V _{SS} - 0.3	0.35	V	1
Operating Supply Current	I _{DD3.3OP}	Full Active, C _L = Full load;		TBD	mA	1
iAMT Mode Current	I _{DDiAMT}			TBD	mA	1
Powerdown Current	I _{DDPD}			TBD	mA	1
Input Frequency	F _i	V _{DD} = 3.3 V		TBD	MHz	2
Pin Inductance	L _{pin}			7	nH	1
Input Capacitance	C _{IN}	Logic Inputs	1.5	5	pF	1
	C _{OUT}	Output pin capacitance		6	pF	1
	C _{INX}	X1 & X2 pins		TBD	pF	1
Clk Stabilization	T _{STAB}	From VDD Power-Up or de-assertion of PD to 1st clock		1.8	ms	1
Tdrive_SRC	T _{DRSRC}	SRC output enable after PCI_STOP# de-assertion		15	ns	1
Tdrive_PD	T _{DRPD}	Differential output enable after PD de-assertion		300	us	1
Tdrive_CPU	T _{DRSRC}	CPU output enable after PCI_STOP# de-assertion		10	ns	1
Tfall_PD	T _{FALL}	Fall/rise time of PD, PCI_STOP# and CPU_STOP# inputs		5	ns	1
Trise_PD	T _{RISE}			5	ns	
SMBus Voltage	V _{DD}		2.7	5.5	V	1
Low-level Output Voltage	V _{OLSMB}	@ I _{PULLUP}		0.4	V	1
Current sinking at V _{OLSMB} = 0.4 V	I _{PULLUP}	SMB Data Pin	4		mA	1
SCLK/SDATA Clock/Data Rise Time	T _{RI2C}	(Max VIL - 0.15) to (Min VIH + 0.15)		1000	ns	1
SCLK/SDATA Clock/Data Fall Time	T _{FI2C}	(Min VIH + 0.15) to (Max VIL - 0.15)		300	ns	1
Maximum SMBus Operating Frequency	F _{SMBUS}			100	kHz	1
Spread Spectrum Modulation Frequency	f _{SSMOD}	Triangular Modulation	30	33	kHz	1

¹Guaranteed by design and characterization, not 100% tested in production.

AC Electrical Characteristics - Low Power Differential (CPUCLK, SATACLK, PCIE_X, DOT96Mhz) Outputs

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS	NOTES
Rising Edge Slew Rate	t_{SLR}	Differential Measurement	2.5	8	V/ns	1,2
Falling Edge Slew Rate	t_{FLR}	Differential Measurement	2.5	8	V/ns	1,2
Slew Rate Variation	t_{SLVAR}	Single-ended Measurement		20	%	1
Maximum Output Voltage	V_{HIGH}	Includes overshoot		1150	mV	1
Minimum Output Voltage	V_{LOW}	Includes undershoot	-300		mV	1
Differential Voltage Swing	V_{SWING}	Differential Measurement	300		mV	1
Crossing Point Voltage	V_{XABS}	Single-ended Measurement	300	550	mV	1,3,4
Crossing Point Variation	$V_{XABSVAR}$	Single-ended Measurement		140	mV	1,3,5
Duty Cycle	D_{CYC}	Differential Measurement	45	55	%	1
CPU Jitter - Cycle to Cycle	$CPUJ_{C2C}$	Differential Measurement		85	ps	1
SRC Jitter - Cycle to Cycle	$SRCJ_{C2C}$	Differential Measurement		125	ps	1
DOT Jitter - Cycle to Cycle	$DOTJ_{C2C}$	Differential Measurement		250	ps	1
CPU[1:0] Skew	CPU_{SKEW10}	Differential Measurement		100	ps	1
CPU[2..ITP:0] Skew	CPU_{SKEW20}	Differential Measurement		150	ps	1
SRC[10:0] Skew	SRC_{SKEW}	Differential Measurement		TBD	ps	1

¹Guaranteed by design and characterization, not 100% tested in production.

² Slew rate measured through Vswing centered around differential zero

³ Vxabs is defined as the voltage where CLK = CLK#

⁴ Only applies to the differential rising edge (CLK rising and CLK# falling)

⁵ Defined as the total variation of all crossing voltages of CLK rising and CLK# falling. Matching applies to rising edge rate of CLK and falling edge of CLK#.

It is measured using a +/-75mV window centered on the average cross point where CLK meets CLK#. The average cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

Electrical Characteristics - PCICLK/PCICLK_F

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS	NOTES
Long Accuracy	ppm	see Tperiod min-max values	-100	100	ppm	1,2
Clock period	T_{period}	33.33MHz output nominal	29.99100	30.00900	ns	2
		33.33MHz output spread		30.15980	ns	2
Absolute min/max period	T_{abs}	33.33MHz output nominal/spread	29.49100	30.65980	ns	2
Output High Voltage	V_{OH}	$I_{OH} = -1 \text{ mA}$	2.4		V	1
Output Low Voltage	V_{OL}	$I_{OL} = 1 \text{ mA}$		0.4	V	1
Output High Current	I_{OH}	$V_{OH} @ \text{MIN} = 1.0 \text{ V}$	-33		mA	1
		$V_{OH} @ \text{MAX} = 3.135 \text{ V}$		-33	mA	1
Output Low Current	I_{OL}	$V_{OL} @ \text{MIN} = 1.95 \text{ V}$	30		mA	1
		$V_{OL} @ \text{MAX} = 0.4 \text{ V}$		38	mA	1
Rising Edge Slew Rate	t_{SLR}	Measured from 0.8 to 2.0 V	1	4	V/ns	1
Falling Edge Slew Rate	t_{FLR}	Measured from 2.0 to 0.8 V	1	4	V/ns	1
Duty Cycle	d_{t1}	$V_T = 1.5 \text{ V}$	45	55	%	1
Skew	t_{skew}	$V_T = 1.5 \text{ V}$		TBD	ps	1
Jitter, Cycle to cycle	$t_{jvc-cyc}$	$V_T = 1.5 \text{ V}$		500	ps	1

¹Guaranteed by design and characterization, not 100% tested in production.

² All Long Term Accuracy and Clock Period specifications are guaranteed assuming that REFOUT is at 14.31818MHz

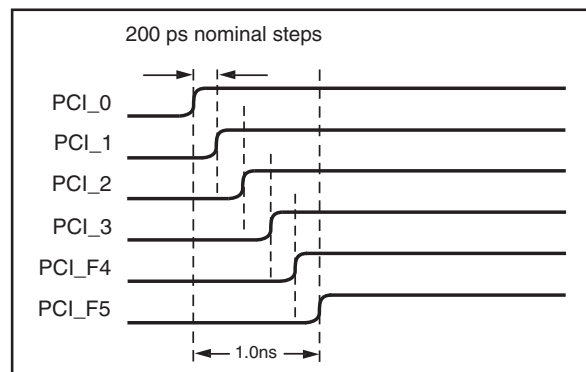
Electrical Characteristics - USB48MHz

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS	NOTES
Long Accuracy	ppm	see Tperiod min-max values	-100	100	ppm	1,2
Clock period	T_{period}	48.00MHz output nominal	20.83125	20.83542	ns	2
Absolute min/max period	T_{abs}	48.00MHz output nominal	20.48130	21.18540	ns	2
Output High Voltage	V_{OH}	$I_{OH} = -1$ mA	2.4		V	1
Output Low Voltage	V_{OL}	$I_{OL} = 1$ mA		0.4	V	1
Output High Current	I_{OH}	$V_{OH} @ MIN = 1.0$ V	-29		mA	1
		$V_{OH} @ MAX = 3.135$ V		-23	mA	1
Output Low Current	I_{OL}	$V_{OL} @ MIN = 1.95$ V	29		mA	1
		$V_{OL} @ MAX = 0.4$ V		27	mA	1
Rising Edge Slew Rate	t_{SLR}	Measured from 0.8 to 2.0 V	1	2	V/ns	1
Falling Edge Slew Rate	t_{FLR}	Measured from 2.0 to 0.8 V	1	2	V/ns	1
Duty Cycle	d_{11}	$V_T = 1.5$ V	45	55	%	1
Jitter, Cycle to cycle	$t_{jcy-cyc}$	$V_T = 1.5$ V		350	ps	1

¹Guaranteed by design and characterization, not 100% tested in production.

² All Long Term Accuracy and Clock Period specifications are guaranteed assuming that REFOUT is at 14.31818MHz

Intentional PCI Clock to Clock Delay



Electrical Characteristics - 27MHz

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
Long Accuracy	ppm	see Tperiod min-max values	-50	0	50	ppm	1,2
			-15	0	15		1,2,3
Clock period	T_{period}	27.000MHz output nominal	37.0365	37.0370	37.0376	ns	2
Output High Voltage	V_{OH}	$I_{OH} = -1$ mA	2.4	3.25		V	1
Output Low Voltage	V_{OL}	$I_{OL} = 1$ mA		0.05	0.55	V	1
Output High Current	I_{OH}	$V_{OH} @ MIN = 1.0$ V	-29	-73		mA	1
		$V_{OH} @ MAX = 3.135$ V		-10	-23	mA	1
Output Low Current	I_{OL}	$V_{OL} @ MIN = 1.95$ V	29	72		mA	1
		$V_{OL} @ MAX = 0.4$ V		27	27	mA	1
Edge Rate	t_{slewrf}	Rising/Falling edge rate	1	2.35	4	V/ns	1
Rise Time	t_{r1}	$V_{OL} = 0.4$ V, $V_{OH} = 2.4$ V	0.5	0.83333333	2	ns	1
Fall Time	t_{f1}	$V_{OH} = 2.4$ V, $V_{OL} = 0.4$ V	0.5	0.86956522	2	ns	1
Duty Cycle	d_{11}	$V_T = 1.5$ V	45	50.5	55	%	1
Jitter	t_{ji}	Long Term (10us)		500	800	ps	1
	t_{pk-pk}		-250	117.5	250	ps	1
	$t_{jcy-cyc}$	$V_T = 1.5$ V		170	500	ps	1

*TA = 0 - 70°C; Supply Voltage VDD = 3.3 V +/-5%, CL = 20 pF with Rs = 7Ω

¹Guaranteed by design and characterization, not 100% tested in production.

² All Long Term Accuracy and Clock Period specifications are guaranteed assuming that REFOUT is at 14.31818MHz

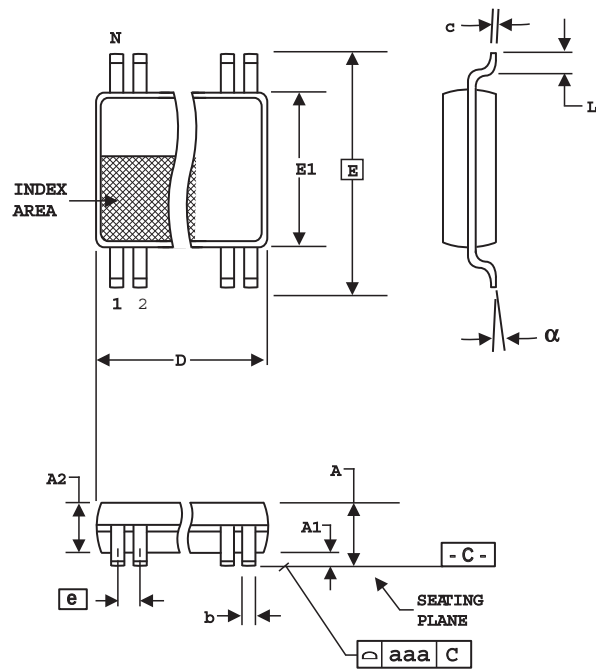
³ At nominal voltage and temperature

Electrical Characteristics - REF-14.318MHz

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS	Notes
Long Accuracy	ppm	see T _{period} min-max values	-100	100	ppm	1,2
Clock period	T _{period}	14.318MHz output nominal	69.8203	69.8622	ns	2
Absolute min/max period	T _{abs}	14.318MHz output nominal	69.8203	70.86224	ns	2
Output High Voltage	V _{OH}	I _{OH} = -1 mA	2.4		V	1
Output Low Voltage	V _{OL}	I _{OL} = 1 mA		0.4	V	1
Output High Current	I _{OH}	V _{OH} @MIN = 1.0 V, V _{OH} @MAX = 3.135 V	-33	-33	mA	1
Output Low Current	I _{OL}	V _{OL} @MIN = 1.95 V, V _{OL} @MAX = 0.4 V	30	38	mA	1
Rising Edge Slew Rate	t _{SLR}	Measured from 0.8 to 2.0 V	1	4	V/ns	1
Falling Edge Slew Rate	t _{FLR}	Measured from 2.0 to 0.8 V	1	4	V/ns	1
Duty Cycle	d _{t1}	V _T = 1.5 V	45	55	%	1
Jitter	t _{ICVC-CVC}	V _T = 1.5 V		1000	ps	1

¹Guaranteed by design and characterization, not 100% tested in production.

² All Long Term Accuracy and Clock Period specifications are guaranteed assuming that REFOUT is at 14.31818MHz



6.10 mm. Body, 0.50 mm. Pitch TSSOP
(240 mil) (20 mil)

SYMBOL	In Millimeters		In Inches	
	COMMON DIMENSIONS		COMMON DIMENSIONS	
	MIN	MAX	MIN	MAX
A	--	1.20	--	.047
A1	0.05	0.15	.002	.006
A2	0.80	1.05	.032	.041
b	0.17	0.27	.007	.011
c	0.09	0.20	.0035	.008
D	SEE VARIATIONS		SEE VARIATIONS	
E	8.10 BASIC		0.319 BASIC	
E1	6.00	6.20	.236	.244
e	0.50 BASIC		0.020 BASIC	
L	0.45	0.75	.018	.030
N	SEE VARIATIONS		SEE VARIATIONS	
alpha	0°	8°	0°	8°
aaa	--	0.10	--	.004

VARIATIONS

N	D mm.		D (inch)	
	MIN	MAX	MIN	MAX
64	16.90	17.10	.665	.673

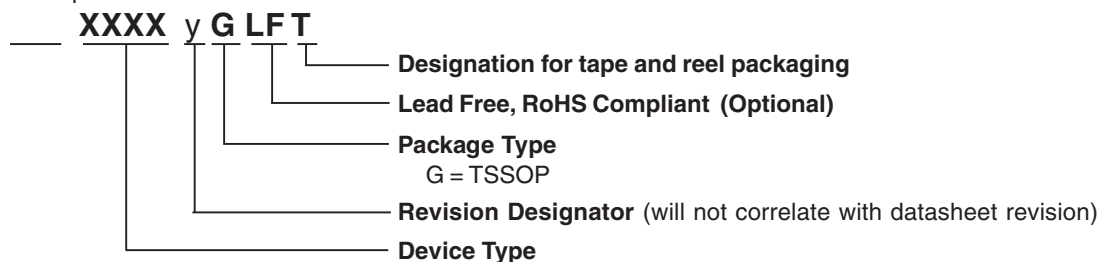
Reference Doc.: JEDEC Publication 95, MO-153

10-0039

Ordering Information

9LPR363yGLFT

Example:





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